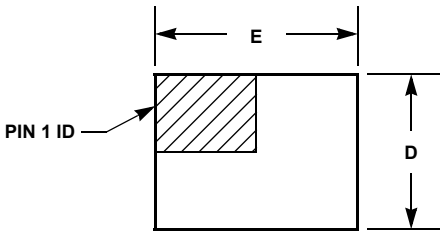
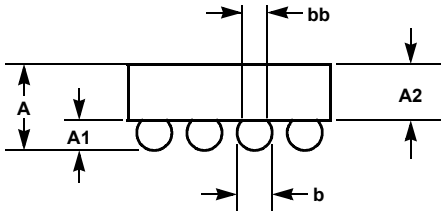
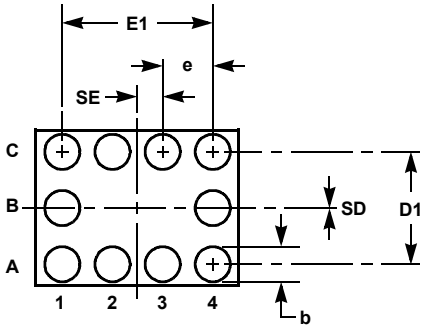
Wafer Level Chip Scale Package (WLCSP)



TOP VIEW



SIDE VIEW



BOTTOM VIEW

W4x3.10A

4X3 ARRAY 10 BALL WAFER LEVEL CHIP SCALE PACKAGE

SYMBOL	MILLIMETERS	NOTES
A	0.64 +0.05 -0.10	-
A1	0.29 ±0.02	-
A2	0.35 REF.	-
b	θ 0.37 ±0.03	-
bb	θ 0.30 REF.	-
D	1.50 ±0.05	-
D1	1.00 BASIC	-
E	2.00 ±0.05	-
E1	1.50 BASIC	-
e	0.50 BASIC	-
SD	0.00 BASIC	-
SE	0.25 BASIC	-
N	10	3

Rev. 1 10/05

NOTES:

1. Dimensions are in Millimeters.
2. Dimensioning and tolerancing conform to ASME 14.5M-1994.
3. Symbol “N” is the actual number of solder balls.